MULTI-COM.PL



Stencil Direct BGA for eMMC/eMCP 221

Product ID: 21691

Price: **8.00 EUR**

Product weight: **0.01 kg**

Description:

Stencil Direct BGA for eMMC/eMCP 221 is used for rebailing BGA memory eMMC / EMCP chips found in phones and tablets.

Go to the product

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